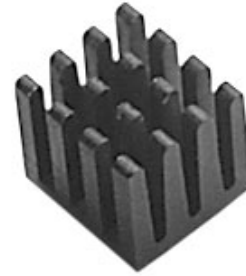


# Board Level Cooling – Extruded 3753



## BOARD LEVEL COOLING - EXTRUDED 3753

3753 is a square pin fin board level heat sink designed to cool BGA and FPGA devices. Representative image only.



## ORDERING INFORMATION

Part Number	Device Type
375324B00035G	BGA, FPGA

## HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Tape
Thermal Interface Material	T411 Chomerics Tape for Plastic Surfaces

Property	Details
Heat Sink Width (mm)	10.20
Heat Sink Length (mm)	10.20
Heat Sink Height (mm)	10.20
Heat Sink Mounting Direction	Horizontal

## MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

